

## DECLARATION

As the below-named inventors, we declare that:

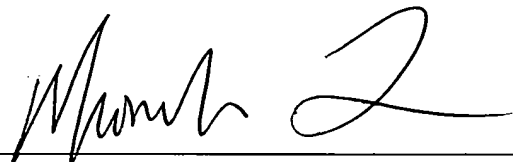
Our residences, post office addresses, and citizenships are as stated below under our names.

We believe we are the original, first, and joint inventors of the subject matter claimed and for which a patent is sought on the invention entitled "METHODS AND APPARATUS FOR ELECTRICAL AND/OR CHEMICALLY-MECHANICALLY REMOVING CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE," as filed in the foregoing specification, and this application is a continuation-in-part of U.S. Application No. 09/651,779 (attorney docket number 108298515US), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000, and U.S. Application No. \_\_\_\_\_ (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate," filed concurrently herewith, and U.S. Application No. \_\_\_\_\_ (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive Material with Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed concurrently herewith, all of which are incorporated herein in their entireties by reference.

We have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

We acknowledge our duty to disclose information of which is material to the patentability of this application in accordance with 37 C.F.R. § 1.56(a), including material information which became available between the filing date of the prior application and the filing date of the present application.

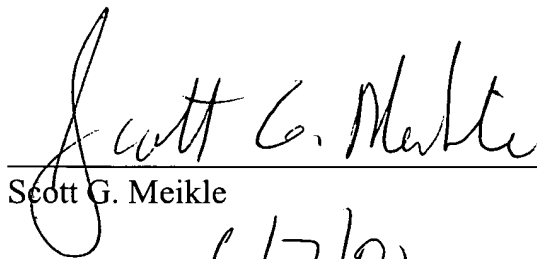
We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.



Whonchee Lee

Date 5/30/01

Residence : City of Boise  
State of Idaho  
Citizenship : United States of America  
P.O. Address : 8998 S. Raptor Lane  
Boise, ID 83709



Scott G. Meikle

Date 6/7/01

Residence : City of Boise  
State of Idaho  
Citizenship : Canadian  
P.O. Address : 1301 E. Jefferson  
Boise, ID 83712

00000000-00000000

Scott E. Moore  
Scott E. Moore

Date 6-05-01

Residence : City of Meridian  
State of Idaho

Citizenship : United States of America

P.O. Address : 1840 E. Mary Lane  
Meridian, ID 83642

0988002-052101

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Whonchee Lee, Scott G. Meikle, Scott E. Moore  
Filed : Concurrently herewith  
For : METHODS AND APPARATUS FOR ELECTRICALLY  
AND/OR CHEMICALLY-MECHANICALLY REMOVING  
CONDUCTIVE MATERIAL FROM A  
MICROELECTRONIC SUBSTRATE

Docket No. : 108298515US3

Box Patent Application  
Assistant Commissioner for Patents  
Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF  
ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventor.

Assignee hereby appoints JERRY A. RIEDINGER, Registration No. 30,582; MAURICE J. PIRIO, Registration No. 33,273; JOHN C. STEWART, Registration No. 40,188; MICHAEL D. BROADDUS, Registration No. 41,637; BRIAN P. MCQUILLEN, Registration No. 41,989; CATHERINE HONG TRAN, Registration No. 43,960; ROBERT G. WOOLSTON, Registration No. 37,263; PAUL T. PARKER, Registration No. 38,264; JOHN M. WECHKIN, Registration No. 42,216; CHRISTOPHER DALEY-WATSON, Registration No. 34,807; STEVEN D. LAWRENZ, Registration No. 37,376; JAMES A.D. WHITE, Registration No.

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43,985; FRANK ABRAMONTE, Registration No. 38,066, and EDWARD S. HOTCHKISS, Registration No. 33,904, along with MICHAEL L. LYNCH, Reg. No. 30,871; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of Micron Technology, Inc., 8000 South Federal Way, Boise, Idaho 83706-9632 as the principal attorneys with full power of substitution, association, and revocation to prosecute said application, to transact all business in the Patent and Trademark Office connected therewith, and to receive the letters patent therefor. Please direct all direct all telephone calls to John M. Wechkin at (206) 583-8888 and telecopies to (206) 583-8500.

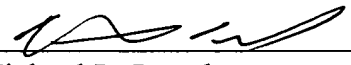
Please direct all communications to:

Patent-SEA  
Perkins Coie LLP  
P. O. Box 1247  
Seattle, Washington 98111-1247  
Attn: John M. Wechkin

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.

6-7-01  
\_\_\_\_\_  
DATE

  
\_\_\_\_\_  
Michael L. Lynch  
Chief Patent Counsel

Enclosure:  
Copy of Assignment

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
 Whonchee Lee ) Docket No.: 108298515US3  
 Scott G. Meikle ) Disclosure Number: 00-1130  
 Scott E. Moore )  
 )  
 Filed: Concurrently herewith )  
 )  
 For: METHODS AND APPARATUS )  
 FOR ELECTRICALLY AND/OR )  
 CHEMICALLY- )  
 MECHANICALLY REMOVING )  
 CONDUCTIVE MATERIAL )  
 FROM A MICROELECTRONIC )  
 SUBSTRATE )  
 \_\_\_\_\_ )

ASSIGNMENT:

☒ Enclosed for recording  
☐ Previously recorded  
 Date: \_\_\_\_\_  
 Reel: \_\_\_\_\_

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, and this application is a continuation-in-part of U.S. Application No. 09/651,779 (attorney docket number 108298515US), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000, and U.S. Application No. \_\_\_\_\_ (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate," filed concurrently herewith, and U.S. Application No. \_\_\_\_\_ (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive

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Material with Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed concurrently herewith, all of which are incorporated herein in their entireties by reference, which has been executed by the undersigned concurrently herewith and is entitled **"METHODS AND APPARATUS FOR ELECTRICALLY AND/OR CHEMICALLY-MECHANICAL AND/OR CHEMICAL REMOVAL OF CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE"**; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

Assignee.



Whorchee Lee

Date: 5/5/01

County of Ada ) ss.

SEAL OF THE NOTARY PUBLIC STATE OF IDAHO

Notary ~~or~~ Consular Officer  
My Commission Expires 6/12/2004

Scott G. Meikle

Date: 6/1/01

County of Ada ) ss.

SEAL  
LORI HIGGENDEN  
NOTARY  
PUBLIC  
STATE OF IDAHO

Notary or Consular Officer  
My Commission Expires 6/12/2004



Scott E. Moore

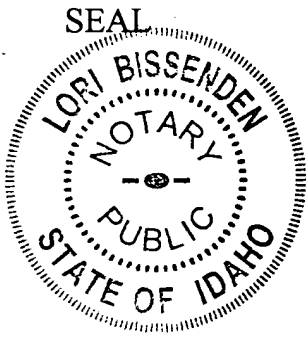
Date: 6-05-01

Scott E. Moore

STATE OF IDAHO )

County of Ada ) ss.

BEFORE ME, this 5<sup>th</sup> day of June, 2001, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.



Lori Bissenden  
Notary or Consular Officer  
My Commission Expires 6/12/2004

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